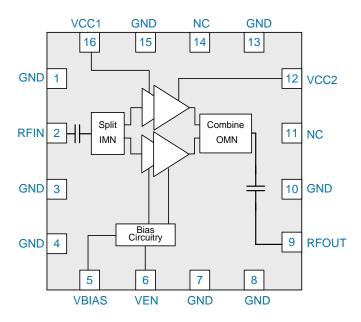


RFMD + TriQuint = Qorvo

# **RFPA0875**

Integrated Power Amplifier Module 869MHz to 894MHz

The RFPA0875 is a two-stage power amplifier (PA) designed for Small Cell Base Stations. Its broadband quadrature design supports usage in multiple bands with excellent output return loss and load tolerance. When used with DPD, the RFPA0875 delivers up to 28dBm LTE Downlink (CFR 8dB) with ACLR -50dBc



Functional Block Diagram

### **Ordering Information**

RFPA0875SQ	Sample bag with 25 pieces
RFPA0875SR	7" Reel with 100 pieces
RFPA0875TR13	13" Reel with 2500 pieces
RFPA0875PCK-410	869MHz to 894MHz PCBA with 5-piece sample bag



Package: Module, 16-pin, 5.0mm x 5.0mm x 1.175mm

#### **Features**

- P<sub>OUT</sub> = 28dBm, 26% PAE, with 5V, 20MHz LTE DL, CFR 8dB
- ACLR -50dBc with DPD
- 29dB Gain
- Integrated Matching to 50Ω
- Integrated DC Block Capacitors
- Broadband Quadrature Design
- Excellent Output Return Loss
- Covers 3GPP Downlink in Band 5
- VSWR Tolerant, Load Insensitive

#### **Applications**

- Small Cell Base Stations
- Data Cards with Terminals
- Customer Premise Equipment



RFMD + TriQuint = Qorvo

#### **Absolute Maximum Ratings**

Parameter	Rating	Unit	
DC Supply Voltage, Vcc (Pout <28dBm, VSWR < 6:1)	6	V	
Enable Control Logic, VEN	+3.3	V	
Maximum Average RF Input Power into 50Ω Load (Vcc = 5.25V)	30	dBm	
Modulated (LTE-20MHz) Input Power 6:1 Output VSWR (V <sub>CC</sub> = 5.25V)	-4	dBm	
Operating Case Temperature	-40 to +85	°C	
Storage Temperature Range	-40 to +150	°C	
Moisture Sensitivity Level (260° JEDEC J-STD-020)	MSL 3		
ESD Rating, All Pins, HBM, JEDEC JS-001	1000	V	
ESD Rating, All Pins, CDM, JEDEC JS-002 1000			



Caution! ESD sensitive device.



RFMD Green: RoHS status based on EU Directive 2011/65/EU (at time of this document revision), halogen free per IEC 61249-2-21, < 1000ppm each of antimony trioxide in polymeric materials and red phosphorus as a flame retardant, and <2% antimony in solder.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

#### **Recommended Operating Condition**

Parameter	S	Unit		
Falanielei	Min	Тур	Max	Onit
Operating Temperature Range	-40		+85	°C
Operating Junction Temperature			180	°C
Power Supply V <sub>CC1</sub> , V <sub>CC2</sub> , V <sub>BIAS</sub>	4.75	5	5.25	V

## **Nominal Operating Parameters**

Parameter Specification		ion	Unit	Our district		
raiailletei	Min	Тур	Max	Unit	Condition	
General Performance						
Operating Frequency Range	869		894	MHz		
V <sub>EN</sub> Range (Logic Low)	0		0.4	V		
V <sub>EN</sub> Range (Logic High)	1.4		3.0	V		
V <sub>EN</sub> Enable Current			0.2	mA	V <sub>EN</sub> = 1.8V	
Total Idle Current (I <sub>CQ</sub> )		110		mA	DC only, V <sub>CC1</sub> = V <sub>CC2</sub> = V <sub>BIAS</sub> = 5V, V <sub>EN</sub> = 1.8V	
VBIAS Current		3		mA	DC only, V <sub>EN</sub> = 1.8V	
DC Enable Time			7	μs	DC only, time from $V_{EN}$ = high to stable idle current (90% of steady state value)	
RF Rise / Fall Time			2	μs	Pouт ≤ 28dBm, 90% of target, DC settled prior to RF	
Thermal Resistance (R <sub>TH</sub> )		31		°C/W	Junction-to-backside of IC	

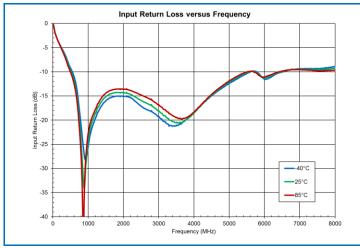


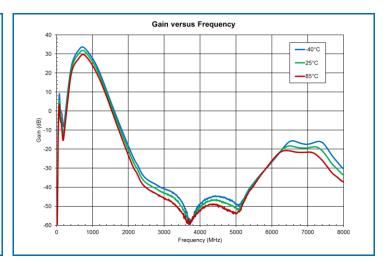
RFMD + TriQuint = Qorvo

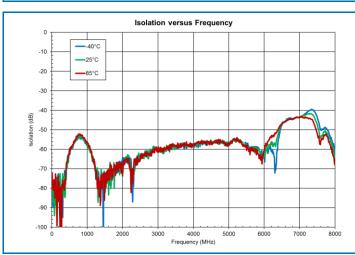
Parameter	Sp	Specification			
rarameter	Min	Тур	Max	Unit	Condition
Electrical Performance: Band 5					Unless Otherwise Specified; Temp = +25°C, $V_{CC}$ = +5.0V, $V_{EN}$ = +1.8V, $P_{OUT}$ = 28dBm, 869MHz < F < 894MHz, $50\Omega$ system, 20MHz LTE DL with CFR 8dB
Gain		29		dB	
ACLR1 – Adjacent Channel		-33		dBc	Without DPD
ACLR2 – Alternate Channel		-46		dBc	Without DPD
ACLR1_DPD		-50		dBc	With DPD
ACLR2_DPD		-56		dBc	With DPD
PA Current Drain		480		mA	With DPD
PAE		26		%	With DPD
Input Return Loss		-25		dB	Small signal S11, no external matching
Output Return Loss		-22		dB	Small signal S22, no external matching
Harmonics 2fo		-27		dBm	
Harmonics 3fo		-50		dBm	
Noise Figure		5.7		dB	Temp = $+25^{\circ}$ C, $V_{CC} = +5$ V, $V_{EN} = +1.8$ V

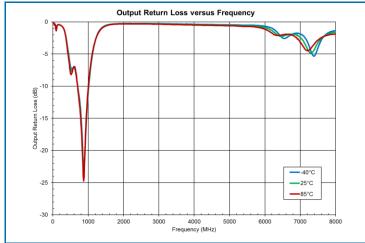


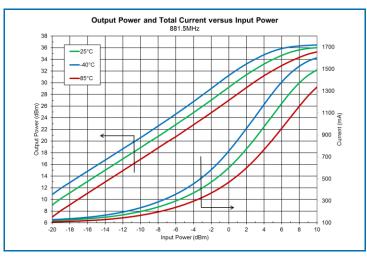
## Typical Performance: V<sub>CC</sub> = V<sub>BIAS</sub> = 5V, V<sub>EN</sub> = 1.8V unless otherwise noted

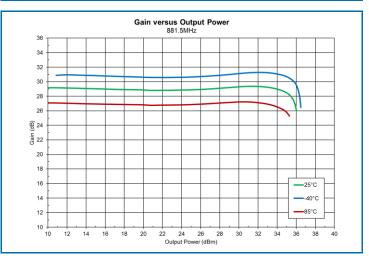






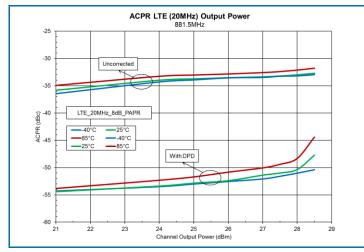


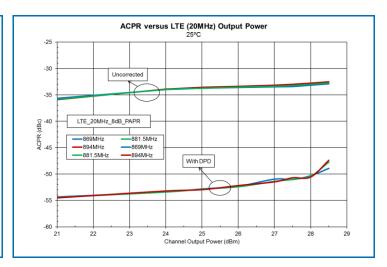


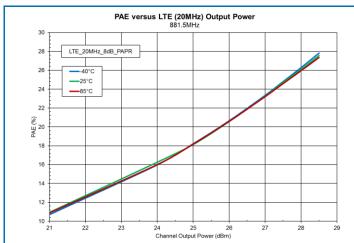


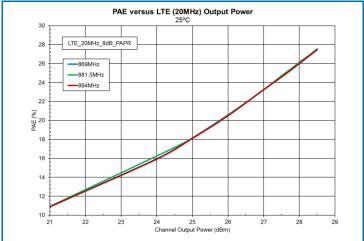


# Typical Performance: Vcc = VBIAS = 5V, VEN = 1.8V unless otherwise noted



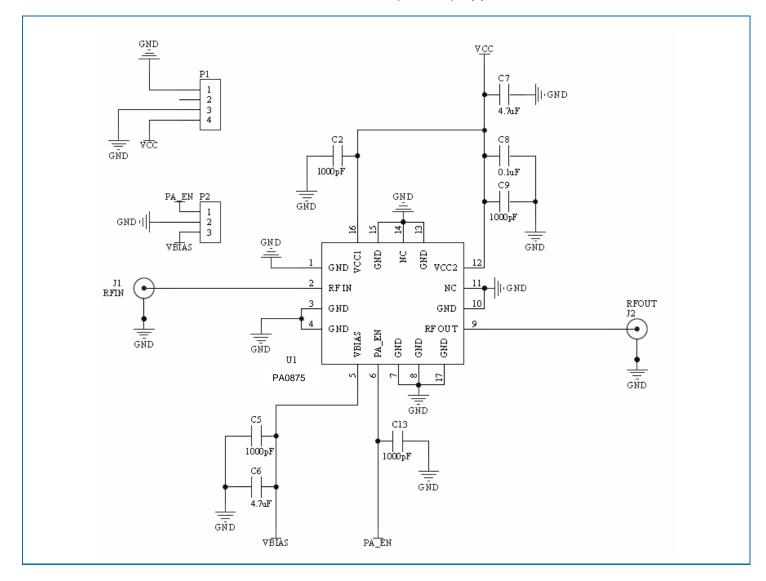








## Evaluation Board Schematic: 869MHz to 894MHz (Band 5) Application Circuit

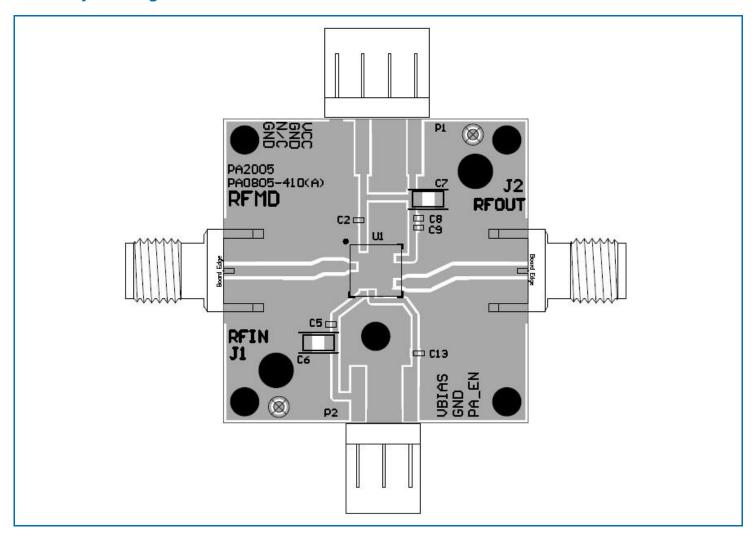




#### Evaluation Board Bill of Materials (BOM) 869MHz to 894MHz (Band 5) Application Circuit

Description	Reference Designator	Manufacturer	Manufacturer's P/N	
RFPA0875 Evaluation Board		Dynamic Details (DDI) Toronto	RFPA0805-410(A)	
869MHz to 894MHz Integrated PA Module	U1	RFMD	RFPA0875	
CAP, 4.7μF, 20%, 10V, X7R, 1206	C6-C7	Taiyo Yuden (USA), Inc.	CE LMK316 B7475ML-T	
CAP, 1000pF, 10%, 50V, X7R, 0402	C2, C5, C9, C13	Murata Electronics	GRM155R71H102KA01D	
CAP, 0.1µF, 10%, 16V, X7R, 0402 MURATA	C8	Murata Electronics	GRM155R71C104KA88D	
CONN, SMA, END, LAUNCH, 0.068"	J1-J2	Gigalane Co., LTD.	PA-S05-008	
CONN, HDR, ST, PLRZD, 4-PIN, 0.100"	P1	ITW Pancon	MPSS100-4-C	
CONN, HDR, ST, PLRZD, 3-PIN, 0.100"	P2	ITW Pancon	MPSS100-3-C	

# **Assembly Drawing**



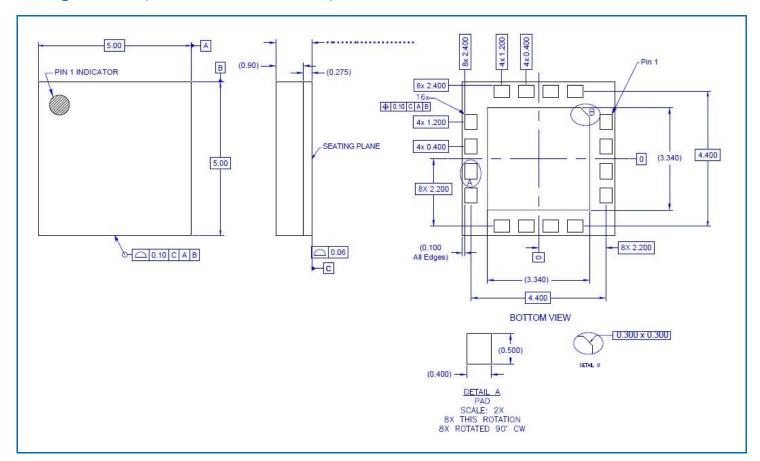


# **Pin Names and Descriptions**

Pin	Name	Description				
1	GND	Ground connection				
2	RF <sub>IN</sub>	RF Input; Internally matched to $50\Omega$				
3	GND	Ground connection				
4	GND	Ground connection				
5	$V_{BIAS}$	Input Bias Voltage				
6	$V_{EN}$	Enable				
7	GND	Ground connection				
8	GND	Ground connection				
9	RF <sub>OUT</sub>	RF Output; Internally matched to $50\Omega$				
10	GND	Ground connection				
11	NC	Not connected				
12	V <sub>CC2</sub>	Output stage collector supply voltage				
13	GND	Ground connection				
14	NC	Not connected , OPEN Circuit in the module				
15	GND	Ground connection				
16	V <sub>CC1</sub>	Drive stage collector supply voltage				
PKG BASE	GND	Ground connection; The back side of the package should be connected to the ground plane though as short of a connection as possible, PCB vias under the device are recommended.				



## Package Outline (Dimensions in millimeters)





#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: www.rfmd.com Tel: 1-844-890-8163

Email: customer.support@qorvo.com

For information about the merger of RFMD and TriQuint as Qorvo:

Web: www.qorvo.com

#### **Important Notice**

The information contained herein is believed to be reliable. RFMD makes no warranties regarding the information contained herein. RFMD assumes no responsibility or liability whatsoever for any of the information contained herein. RFMD assumes no responsibility or liability whatsoever for the use of the information contained herein. The information contained herein is provided "AS IS, WHERE IS" and with all faults, and the entire risk associated with such information is entirely with the user. All information contained herein is subject to change without notice. Customers should obtain and verify the latest relevant information before placing orders for RFMD products. The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information.

RFMD products are not warranted or authorized for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death.